

SEMICONDUCTOR PACKAGE WITH POSITION MEMBER AND METHOD OF MANUFACTURING THE SAME

ABSTRACT

The present invention provides a very thin semiconductor package **10** that comprises a leadframe with a die-attach pad **12** and a plurality of lead terminals **11**, a die **13** attached to the die-attach pad **12** and electrically connected to the lead terminals **11** via bonding wires **14**, a position member **15, 16** disposed upon the die and/or die-attach pad, and a molding material **17** encapsulating the leadframe, the die, and the position member together to form the semiconductor package. The present invention further provides a method for manufacturing a very thin semiconductor package. The method comprises the steps of disposing a first position member on one side of the die-attach pad of a leadframe, attaching a die onto the opposite side of the die-attach pad, optionally disposing a second position member on top of the die, electrically connecting the die to the lead terminals of the leadframe, and encapsulating the leadframe, the die, and the position member(s) together to form the very thin semiconductor package.

FIG 2A